

General Description

The AOD454A uses advanced trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. With the excellent thermal resistance of the DPAK package, this device is well suited for high current load applications.

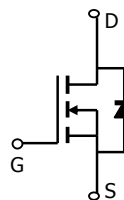
Features

V_{DS} (V) = 40V

I_D = 20A (V_{GS} = 10V)

$R_{DS(ON)}$ < 30m Ω (V_{GS} = 10V)

$R_{DS(ON)}$ < 40m Ω (V_{GS} = 4.5V)



Absolute Maximum Ratings $T_A=25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Maximum	Units
Drain-Source Voltage	V_{DS}	40	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current ^{B,H}	I_D	$T_C=25^\circ\text{C}$	20
		$T_C=100^\circ\text{C}$	15
Pulsed Drain Current ^C	I_{DM}	40	A
Avalanche Current ^C	I_{AR}	14	
Repetitive avalanche energy $L=0.1\text{mH}$ ^C	E_{AR}	9.8	mJ
Power Dissipation ^B	P_D	$T_C=25^\circ\text{C}$	37
		$T_C=100^\circ\text{C}$	18
Power Dissipation ^A	P_{DSM}	$T_A=25^\circ\text{C}$	2.5
		$T_A=70^\circ\text{C}$	1.6
Junction and Storage Temperature Range	T_J, T_{STG}	-55 to 175	$^\circ\text{C}$

Thermal Characteristics

Parameter	Symbol	Typ	Max	Units
Maximum Junction-to-Ambient ^{A,G}	$R_{\theta JA}$	$t \leq 10\text{s}$	16.7	25
Maximum Junction-to-Ambient ^{A,G}		Steady-State	40	50
Maximum Junction-to-Case ^F	$R_{\theta JC}$	3	4	$^\circ\text{C/W}$

Electrical Characteristics (T_J=25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
STATIC PARAMETERS						
BV _{DSS}	Drain-Source Breakdown Voltage	I _D =250μA, V _{GS} =0V	40			V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =40V, V _{GS} =0V T _J =55°C			1 5	μA
I _{GSS}	Gate-Body leakage current	V _{DS} =0V, V _{GS} = ±20V			±100	nA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} I _D =250μA	1.7	2.5	3	V
I _{D(ON)}	On state drain current	V _{GS} =10V, V _{DS} =5V	40			A
R _{DS(ON)}	Static Drain-Source On-Resistance	V _{GS} =10V, I _D =12A T _J =125°C		24 37	30 46	mΩ
		V _{GS} =4.5V, I _D =8A		30	40	
g _{FS}	Forward Transconductance	V _{DS} =5V, I _D =12A		25		S
V _{SD}	Diode Forward Voltage	I _S =1A, V _{GS} =0V		0.76	1	V
I _S	Maximum Body-Diode Continuous Current				2.5	A
DYNAMIC PARAMETERS						
C _{iss}	Input Capacitance	V _{GS} =0V, V _{DS} =20V, f=1MHz		516	650	pF
C _{oss}	Output Capacitance			82		pF
C _{rss}	Reverse Transfer Capacitance			43		pF
R _g	Gate resistance	V _{GS} =0V, V _{DS} =0V, f=1MHz		4.6		Ω
SWITCHING PARAMETERS						
Q _g	Total Gate Charge	V _{GS} =10V, V _{DS} =20V, I _D =12A		8.3	10.8	nC
Q _{gs}	Gate Source Charge			2.3		nC
Q _{gd}	Gate Drain Charge			1.6		nC
t _{D(on)}	Turn-On Delay Time	V _{GS} =10V, V _{DS} =20V, R _L =1.6Ω, R _{GEN} =3Ω		6.4		ns
t _r	Turn-On Rise Time			3.6		ns
t _{D(off)}	Turn-Off Delay Time			16.2		ns
t _f	Turn-Off Fall Time			6.6		ns
t _{rr}	Body Diode Reverse Recovery Time	I _F =12A, di/dt=100A/μs		18	24	ns
Q _{rr}	Body Diode Reverse Recovery Charge	I _F =12A, di/dt=100A/μs		10		nC

A: The value of R_{θJA} is measured with the device in a still air environment with T_A=25°C. The power dissipation P_D and current rating I_D are based on T_{J(MAX)}=150°C, using t ≤ 10s junction-to-ambient thermal resistance.

B: The power dissipation P_D is based on T_{J(MAX)}=175°C, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heatsinking is used.

C: Repetitive rating, pulse width limited by junction temperature T_{J(MAX)}=175°C.

D: The R_{θJA} is the sum of the thermal impedance from junction to case R_{θJC} and case to ambient.

E: The static characteristics in Figures 1 to 6 are obtained using <300 μs pulses, duty cycle 0.5% max.

F: These curves are based on the junction-to-case thermal impedance which is measured with the device mounted to a large heatsink, assuming a maximum junction temperature of T_{J(MAX)}=175°C. The SOA curve provides a single pulse rating.

G: These tests are performed with the device mounted on 1 in² FR-4 board with 2oz. Copper, in a still air environment with T_A=25°C.

H: The maximum current rating is limited by bond-wires.

*This device is guaranteed green after data code 8X11 (Sep 1ST 2008).

Rev3: July 2010

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

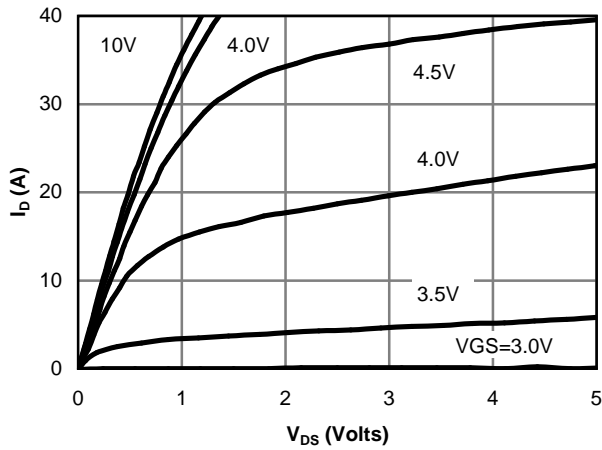


Figure 1: On-Region Characteristics

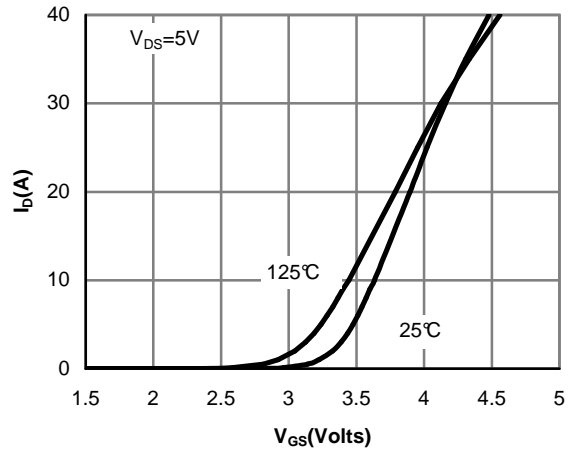


Figure 2: Transfer Characteristics

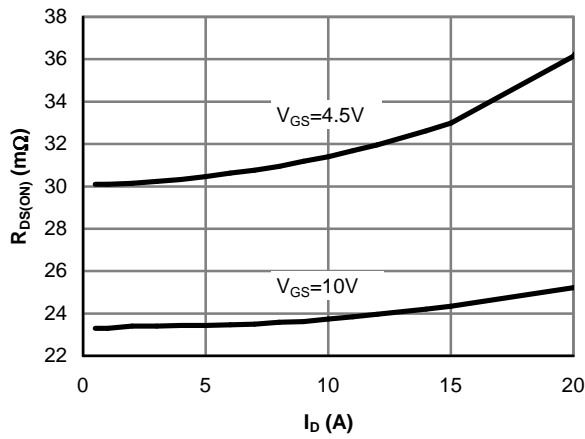


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

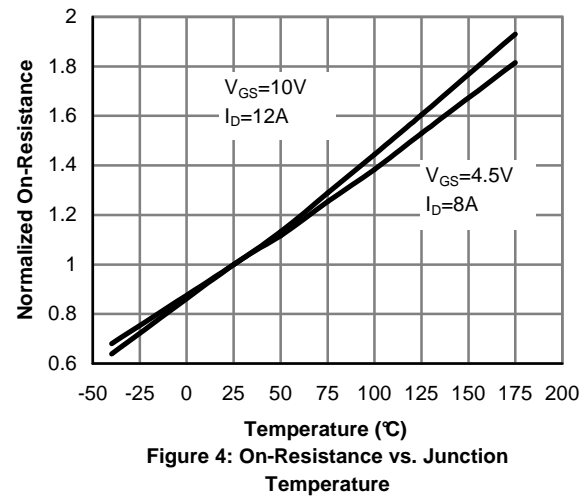


Figure 4: On-Resistance vs. Junction Temperature

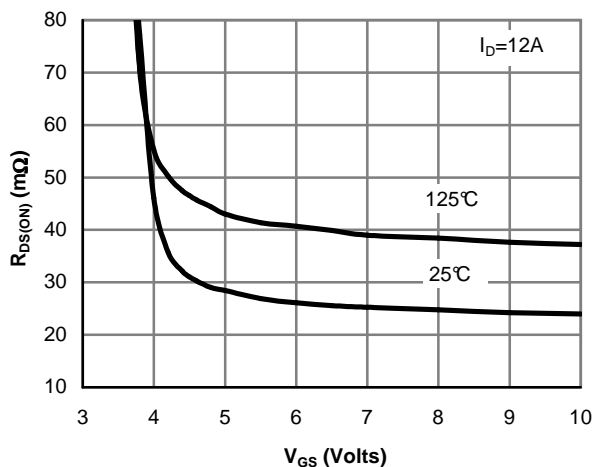


Figure 5: On-Resistance vs. Gate-Source Voltage

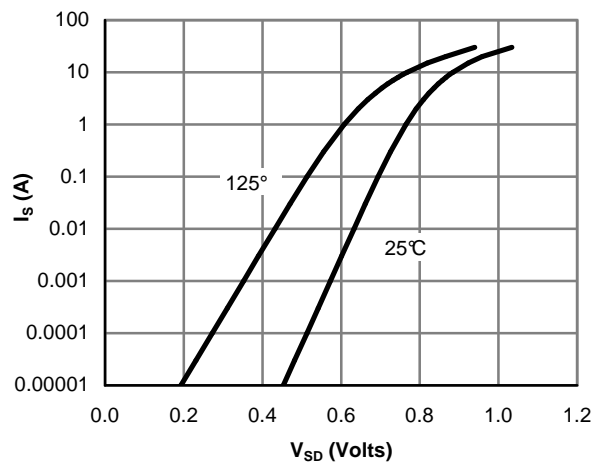


Figure 6: Body-Diode Characteristics

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

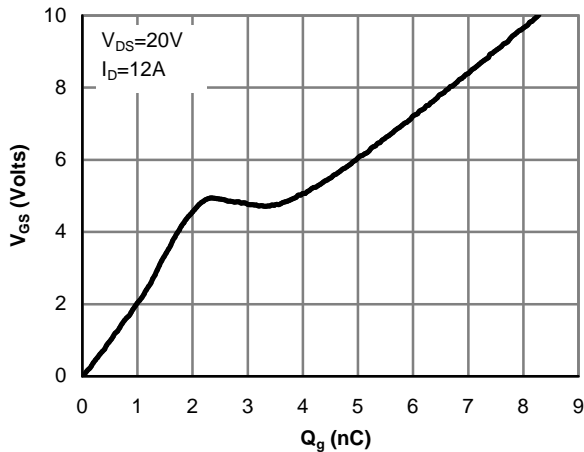


Figure 7: Gate-Charge Characteristics

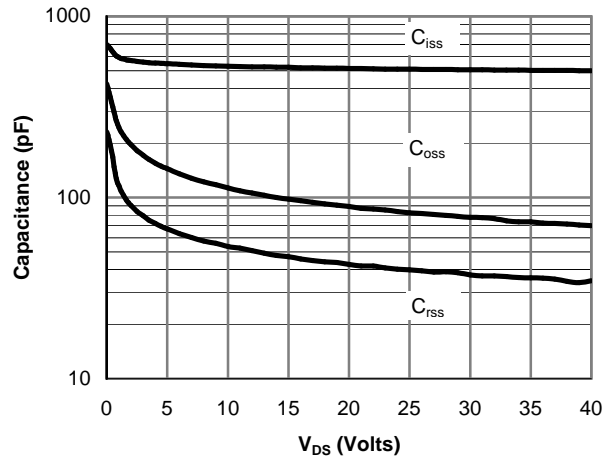


Figure 8: Capacitance Characteristics

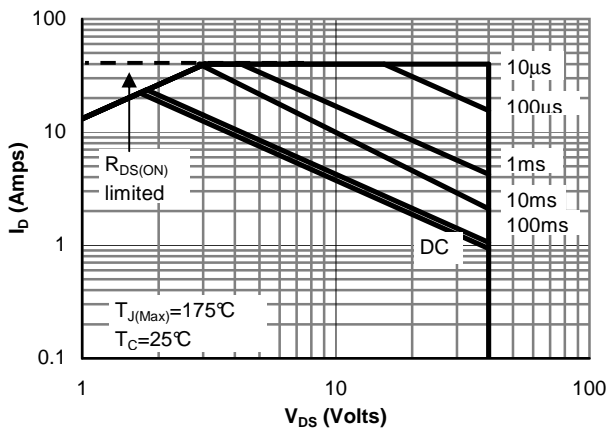


Figure 9: Maximum Forward Biased Safe Operating Area (Note F)

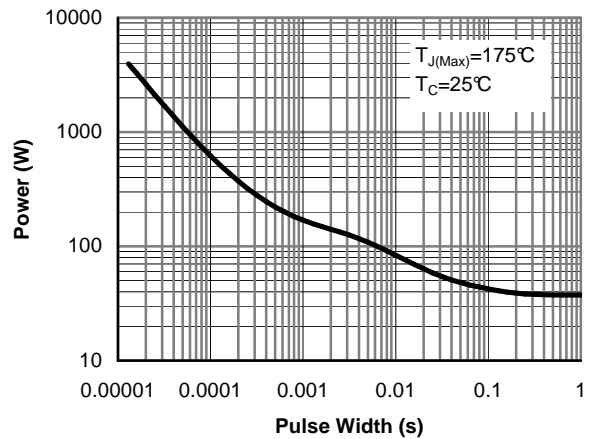


Figure 10: Single Pulse Power Rating Junction-to-Case (Note F)

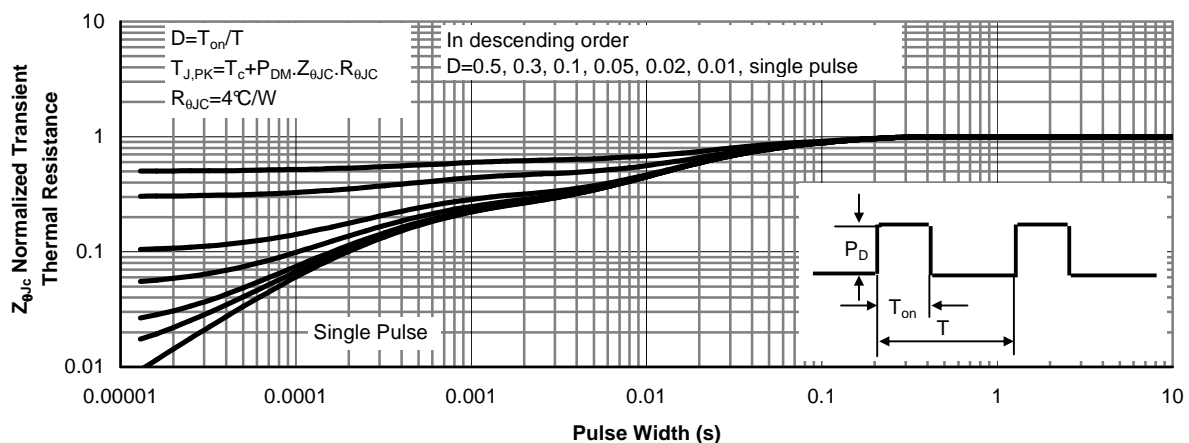


Figure 11: Normalized Maximum Transient Thermal Impedance (Note F)

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

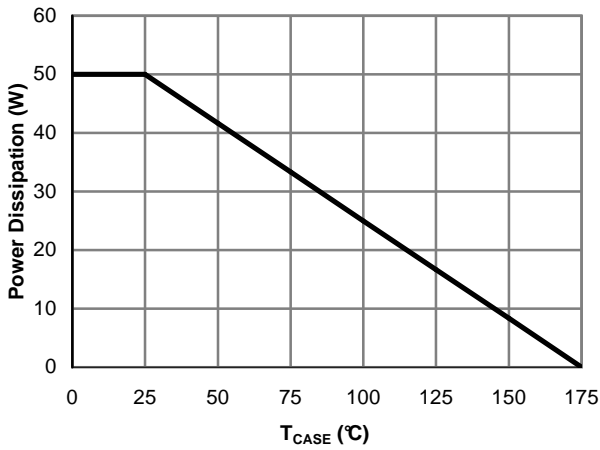


Figure 12: Power De-rating (Note B)

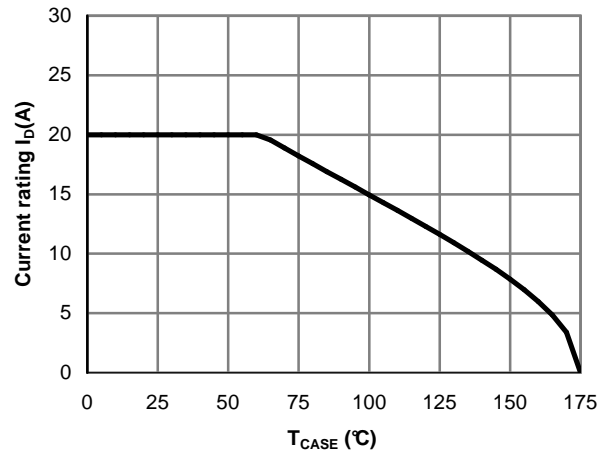


Figure 13: Current De-rating (Note B)

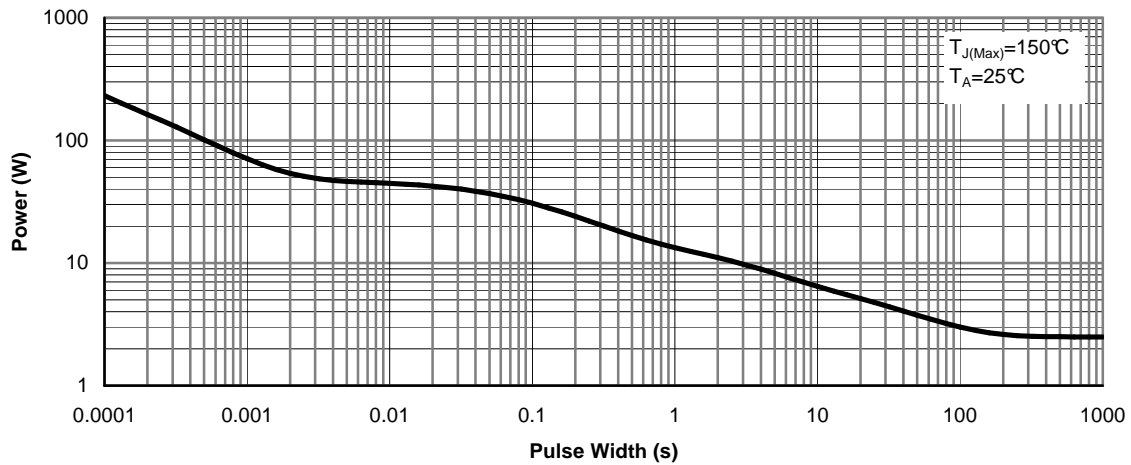


Figure 14: Single Pulse Power Rating Junction-to-Ambient (Note G)

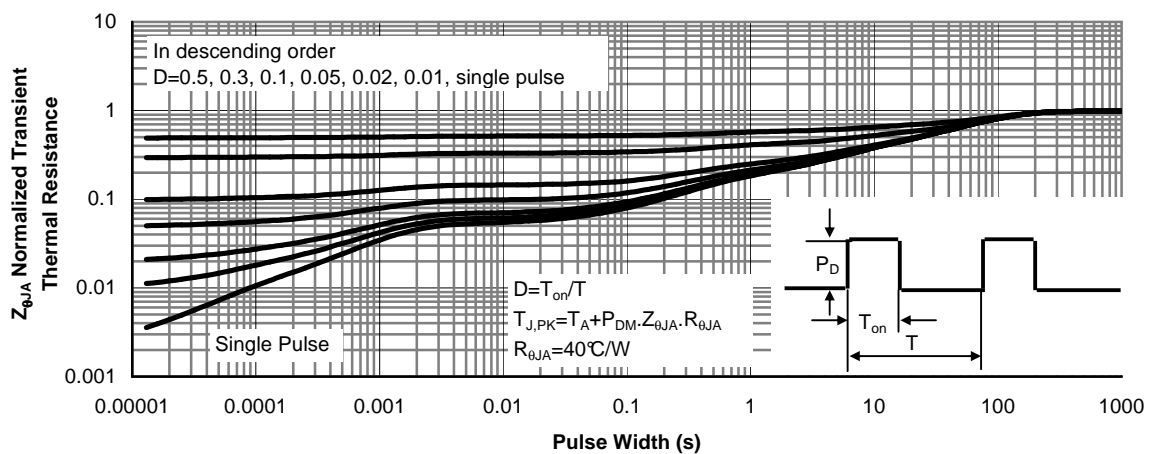
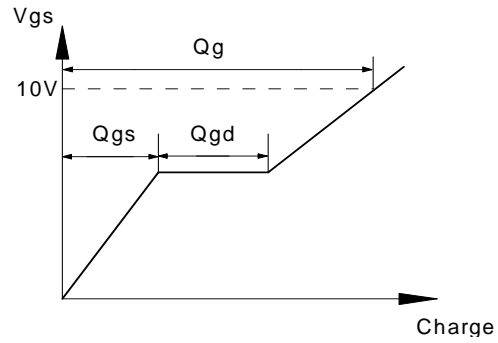
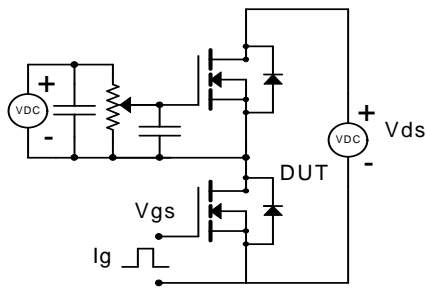
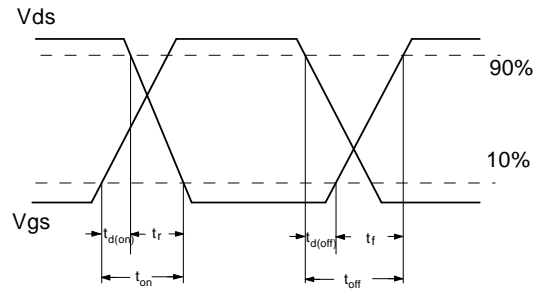
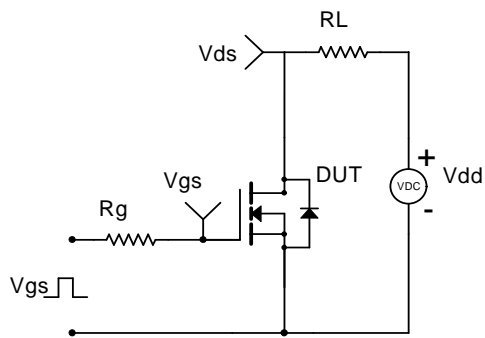


Figure 15: Normalized Maximum Transient Thermal Impedance (Note G)

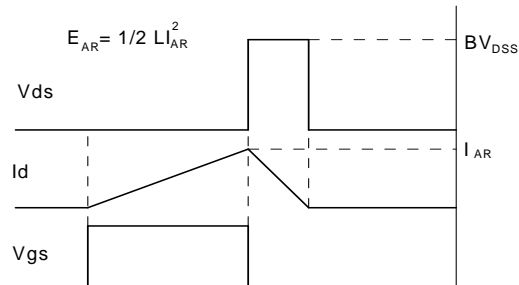
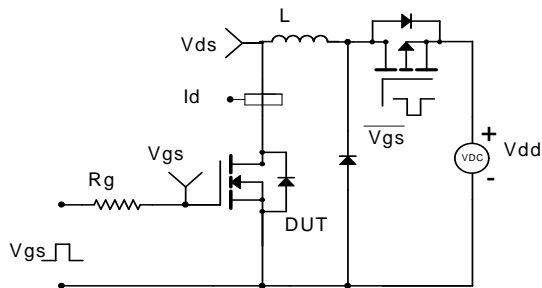
Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms

